

SID

Factory: Rot am See

Article:

ML10

Provided:

Customer:

Date:

03.04.2026



WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	260		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		
		35	L2	
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	203		
		35	L3	
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	216		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		
		35	L4	
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	203		
		35	L5	
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	216		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		
		35	L6	
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	203		
		35	L7	
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	216		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		
		35	L8	
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	203		
		35	L9	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	260		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2330 µm

Version 1.2.20.35

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